# RENESAS

# M62009L/P/FP

Low Power 2 Output System Reset IC with External Input

REJ03D0782-0100 Rev.1.00 Sep 14, 2005

## Description

As applications for microcomputers are increasing, a desire has arisen for a RAM backup function. Let us introduce Renesas new low power dissipation, high-performance system reset IC, which is suitable for such RAM backup.

The M62009, which is a low power dissipation 2-output microcomputer system reset IC, is a 2-output system reset IC which provides for RAM backup in microcomputers, and reduces power dissipation by using the Bi-CMOS process. The M62009 considerably reduces the number of components in the reset circuit.

The M62009 performs two-step detection of normal supply voltage and backup supply voltage required for backup mode. When the supply voltage is switched from normal supply voltage to backup supply voltage the interruption output, which is one of the two outputs, gives the interruption signal to a microcomputer, in this way, the microcomputer reduces power dissipation and enters in the backup mode. If the backup supply voltage goes lower than the voltage required for backup, the reset output (RESET output) which is different from the INT output gives the reset signal (forced reset) to the microcomputer. The interruption signal from the INT output recovers the microcomputer from the backup mode. To recover from reset, RESET output is canceled when the specified interval of time (delay time) elapses after the signal is given from the INT output.

# Features

- Bi-CMOS process realizes a configuration of low current dissipating circuits.
  - $I_{CC} = 7 \ \mu A \ (Typ, normal mode, V_{CC1} = V_{CC2} = 5.0 \ V)$
  - $I_{CC} = 5 \ \mu A \ (Typ, backup mode, V_{CC1} = 5.0 \ V)$
  - $I_{CC} = 1 \ \mu A \ (Typ, backup mode, V_{CC1} = 2.5 \ V)$
  - Two-step detection of supply voltage
  - $V_{CC1}$  (RESET):
    - $V_{S1-1} = 4.0 V$  (Typ, increase of  $V_{CC1}$ )
    - $V_{S1-2} = 2.0 V$  (Typ, decrease of  $V_{CC1}$ )

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V_{CC2} (\overline{INT}):
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Free setup
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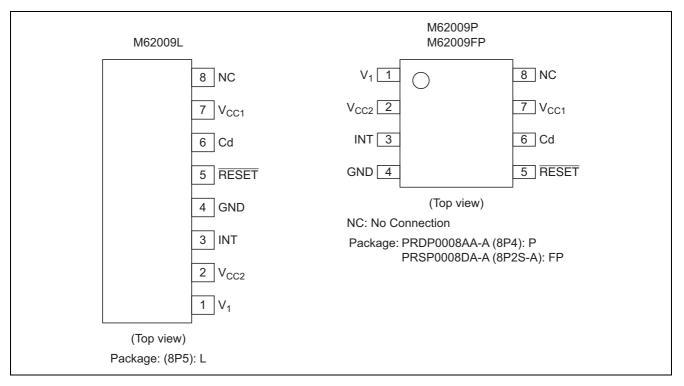
- Two outputs (open drain type) Reset output (RESET): Forced reset signal output Interruption output (INT): Output of the signal for interruption processing (output of the switching signal for backup mode)
- Three types of outline packages
   8-pin plastic SIP (single in-line package)
   8-pin plastic DIP (dual in-line package)
   8-pin plastic SOP (mini flat package)
- Output based on RAM backup mode (see the timing chart)

# Application

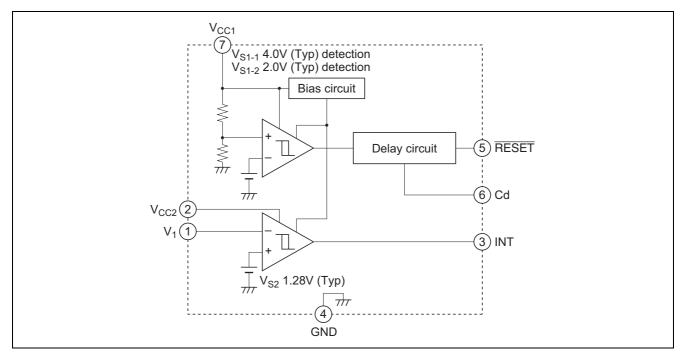
• Prevention of errors in microcomputer system in electronic equipment that requires RAM backup, such as office, industrial, and home-use equipment.



## **Pin Arrangement**



# **Block Diagram**





# Absolute Maximum Ratings

			$(Ta = 25^{\circ}C, unless otherwise noted)$		
ltem	Symbol	Ratings	Unit	Conditions	
Supply voltage	V <sub>CC</sub>	8	V		
Output sink current	Isink	5	mA		
Power dissipation	Pd	800	mW	8-pin SIP	
		625		8-pin DIP	
		440		8-pin SOP	
Thermal derating	Κθ	4.4	mW/°C	Ta ≥ 25°C	
Operating temperature	Topr	-20 to +75	°C		
Storage temperature	Tstg	-40 to +125	°C		

# **Electrical Characteristics**

 $(Ta = 25^{\circ}C, unless otherwise noted)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Detection voltage	V <sub>S1-1</sub>	3.8	4.0	4.2	V	Increase of V <sub>CC1</sub>
	V <sub>S1-2</sub>	1.85	2.00	2.15		Decrease of V <sub>CC1</sub>
Reference voltage	V <sub>S2</sub>	1.23	1.28	1.33	V	Decrease of V <sub>1</sub>
Hysteresis voltage	$\Delta V_S$	—	87	—	mV	V <sub>CC2</sub> = Detection voltage of hysteresis voltage (Detection voltage = 4V setup)
Circuit current	I <sub>CC1</sub>	—	7	15	μΑ	$V_{CC1} = V_{CC2} = 5V$
	I <sub>CC2-1</sub>	—	5	10		$V_{CC1} = 5V, V_{CC2} = 0V$
	I <sub>CC2-2</sub>	—	1	3		$V_{CC1} = 2.5V, V_{CC2} = 0V$
Delay time	t <sub>d</sub>	—	50	—	ms	Cd = 0.33µF
Output saturation voltage	Vsat	—	0.2	0.4	V	$V_{IN} = 5V, I_O = 4mA (NMOS)$
Reset output response time	t <sub>RESET</sub>	—	30	—	μS	Time between $V_{CC1}$ (when falling) = $V_{S1-2}$ and output of <b>RESET</b> signal
Interruption output reset time	t <sub>INT</sub>	—	100	—	μS	Time between $V_{CC2}$ (when falling) = $V_{S2}$ and output of $\overline{INT}$ signal



# **Operating Description**

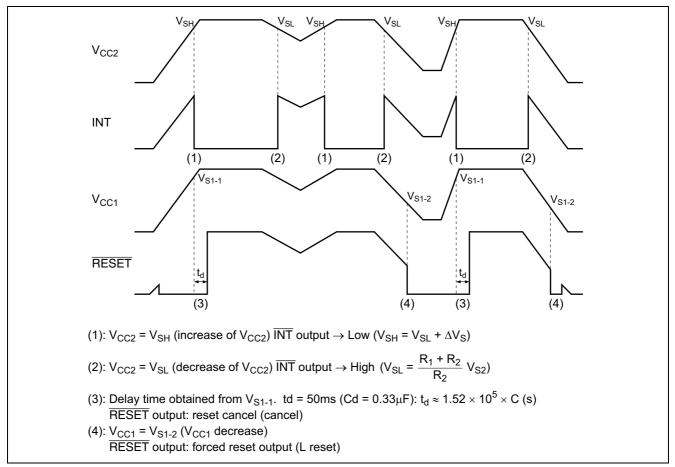


Figure 1 Operating Waveform

# **Application Example**

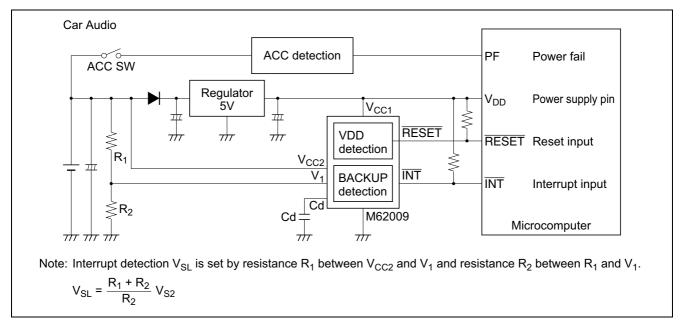
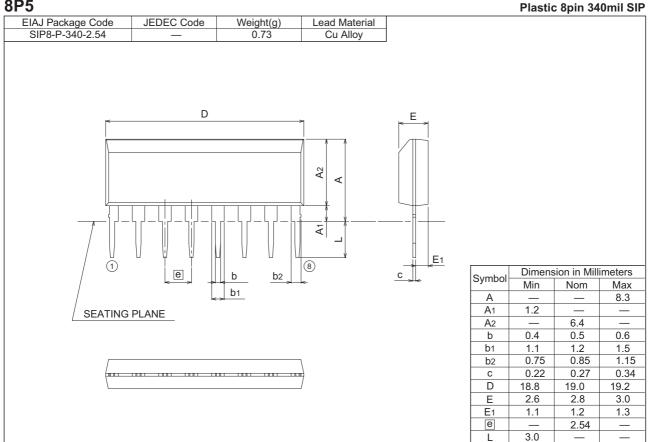
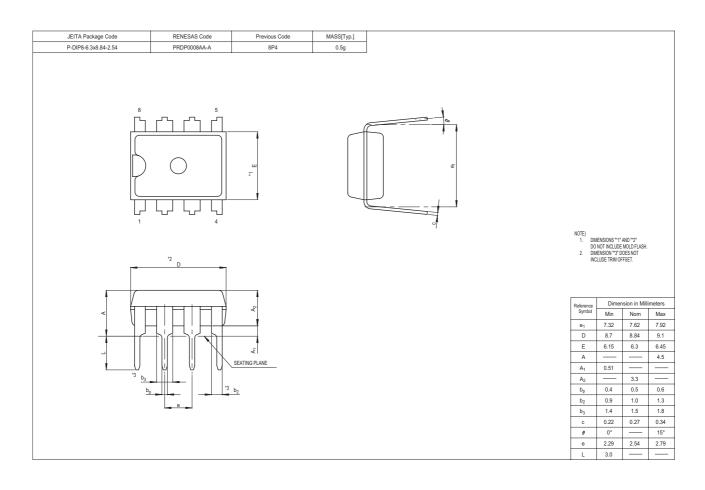


Figure 2 Application Example

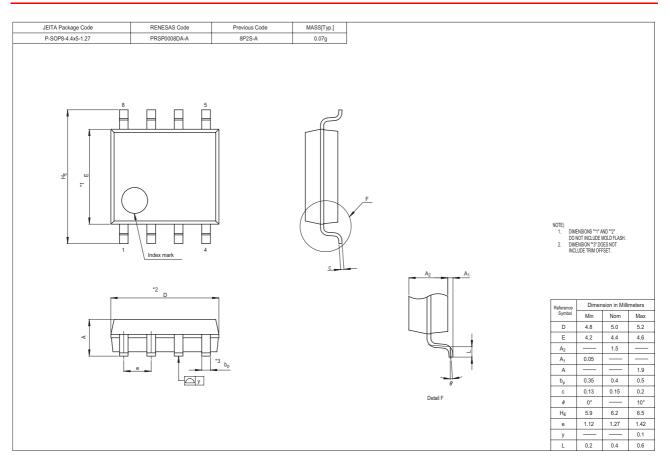
# **Package Dimensions**

### 8P5











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